

Application No. 09/484,437
Office Action dated September 20, 2006
Date of Reply to Office Action: December 20, 2006

Docket No.: M4065.0226/P226

AMENDMENTS TO THE SPECIFICATION

Please amend the title as follows:

PREPACKAGED SEMICONDUCTOR DEVICE ASSEMBLY HAVING A PARTIALLY
CURED ADHESIVE ~~DIE ATTACH CURING METHOD FOR SEMICONDUCTOR DEVICE~~